

# Limeng Yin

## List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/4784305/publications.pdf>

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18  
papers

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1163117

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1199594

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19  
docs citations

19  
times ranked

106  
citing authors

#	ARTICLE	IF	CITATIONS
1	Interfacial microstructure evolution and properties of Sn-0.3Ag-0.7Cu-xSiC solder joints. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2021, 809, 140995.	5.6	22
2	The effect of joint size on the creep properties of microscale lead-free solder joints at elevated temperatures. Journal of Materials Science: Materials in Electronics, 2013, 24, 1369-1374.	2.2	20
3	Effects of Location on the Microstructure and Mechanical Properties of Cu-8Al-2Ni-2Fe-2Mn Alloy Produced Through Wire Arc Additive Manufacturing. Journal of Materials Engineering and Performance, 2020, 29, 4733-4744.	2.5	15
4	Microstructures and their distribution within HAZ of X80 pipeline steel welded using hybrid laser-MIG welding. Welding in the World, Le Soudage Dans Le Monde, 2018, 62, 721-727.	2.5	14
5	Prediction of weld formation in 5083 aluminum alloy by twin-wire CMT welding based on deep learning. Welding in the World, Le Soudage Dans Le Monde, 2019, 63, 947-955.	2.5	14
6	Quantitative Correlation between Thermal Cycling and the Microstructures of X100 Pipeline Steel Laser-Welded Joints. Materials, 2020, 13, 121.	2.9	13
7	Microstructures and properties of Sn-0.3Ag-0.7Cu solder doped with graphene nanosheets. Journal of Materials Science: Materials in Electronics, 2020, 31, 1861-1867.	2.2	10
8	Effects of Graphene Nanosheets on the Wettability and Mechanical Properties of Sn-0.3Ag-0.7Cu Lead-Free Solder. Journal of Electronic Materials, 2020, 49, 7394-7399.	2.2	9
9	Effect of Ti Content on the Microstructure and Properties of CoCrFeNiMnTi <sub>x</sub> High Entropy Alloy. Entropy, 2022, 24, 241.	2.2	9
10	Magnetocaloric effect in Ni-Fe-Mn-Sn microwires with nano-sized $\hat{\text{I}}^3$ precipitates. Applied Physics Letters, 2020, 116, .	3.3	8
11	Effects of Sn addition on the microstructure and properties of Bi-11Ag high-temperature solder. Journal of Materials Science: Materials in Electronics, 2018, 29, 12028-12035.	2.2	7
12	Microstructures and properties of Bi 10Ag high temperature solder doped with Cu element. Microelectronics Reliability, 2018, 80, 79-84.	1.7	6
13	The Evolution and Distribution of Microstructures in High-Energy Laser-Welded X100 Pipeline Steel. Materials, 2019, 12, 1762.	2.9	5
14	Molecular dynamics simulation of the interfacial evolution and whisker growth of copper-tin coating under electrothermal coupling. Computational Materials Science, 2022, 202, 110981.	3.0	5
15	Effect of Cu Addition on the Microstructure and Mechanical Properties of Sn-58Bi-0.5Ag Solder Alloys. Journal of Electronic Materials, 2022, 51, 3552-3559.	2.2	4
16	Effects of Joint Height on the Interfacial Microstructure and Mechanical Properties of Cu-Cored SAC305 Solder Joints. Journal of Electronic Materials, 2020, 49, 5391-5398.	2.2	3
17	Effect of Ni content on the creep properties of Cu/Sn-0.3Ag-0.7Cu/Cu solder micro-joints. Journal of Materials Science: Materials in Electronics, 2020, 31, 5462-5470.	2.2	3
18	Experimental and numerical simulation of mechanical behavior of micro-scale SAC305 solder joint based on joint height. Welding in the World, Le Soudage Dans Le Monde, 2020, 64, 2101-2108.	2.5	1